

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	108	216/13-18.ccls. and (solder adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:55
L2	106	216/13-18.ccls. and (solder adj mask) and (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:56
L3	90	216/13-18.ccls. and (solder adj mask) and (board or substrate) and (conductor or pattern)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:56
L4	131	29/847-853.ccls. and (solder adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:56
L5	134	174/255-256.ccls. and (solder adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:57
L6	305	174/260-264.ccls. and (solder adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:57
L7	57	361/792-795.ccls. and (solder adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:59
L8	16	2 and (CTE or coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:58
L9	59	428/209-210.ccls. and (solder adj mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2005/03/28 08:59